

ASMNUT.001A



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Uzoh et al.
App. No. : 10/769,605
Filed : January 30, 2004
For : METHOD OF
ELECTROPLATING COPPER
LAYERS WITH FLAT
TOPOGRAPHY
Examiner : William T. Leader

I hereby certify that this correspondence and all marked attachments are being deposited with the United States Postal Service as first-class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on

July 29, 2005

(Date)

Tina Chen, Reg. No. 44,606

STATUS LETTER

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Our file for the above-identified application reveals that there has been no action taken since the application was filed, i.e. January 30, 2004. Please inform us as to the status of this application.

Respectfully submitted,

KNOBBE, MARTENS, OLSON & BEAR, LLP

Dated: July 29, 2005

By: 

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